



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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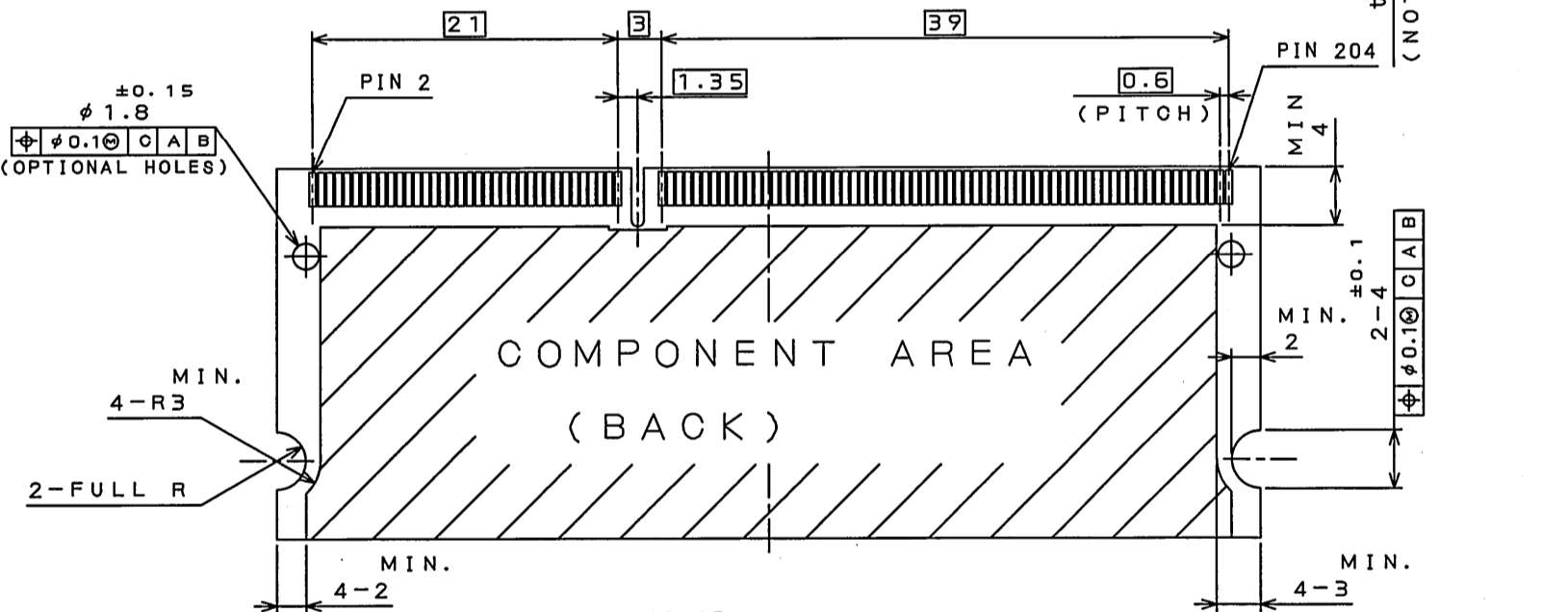
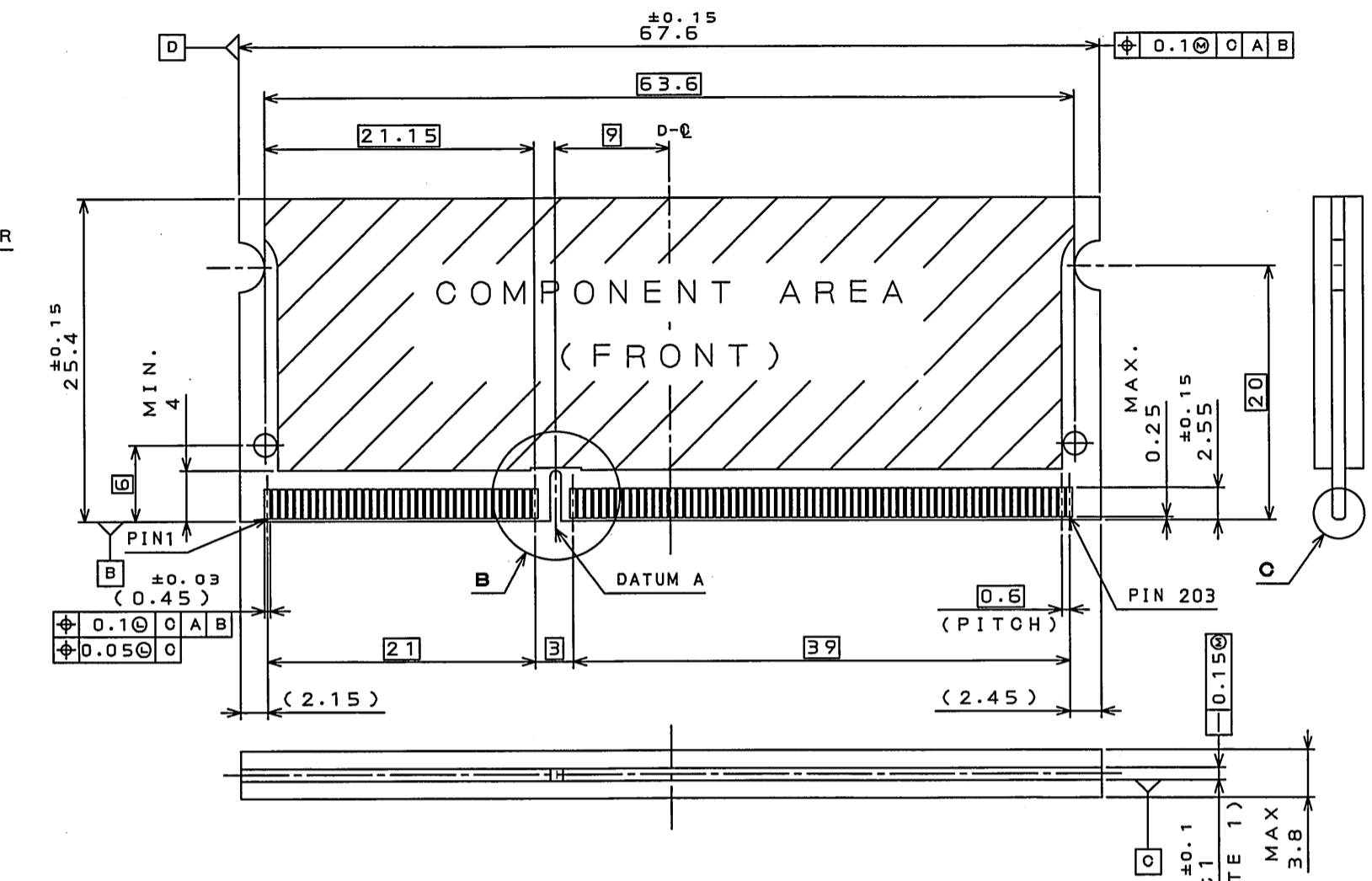
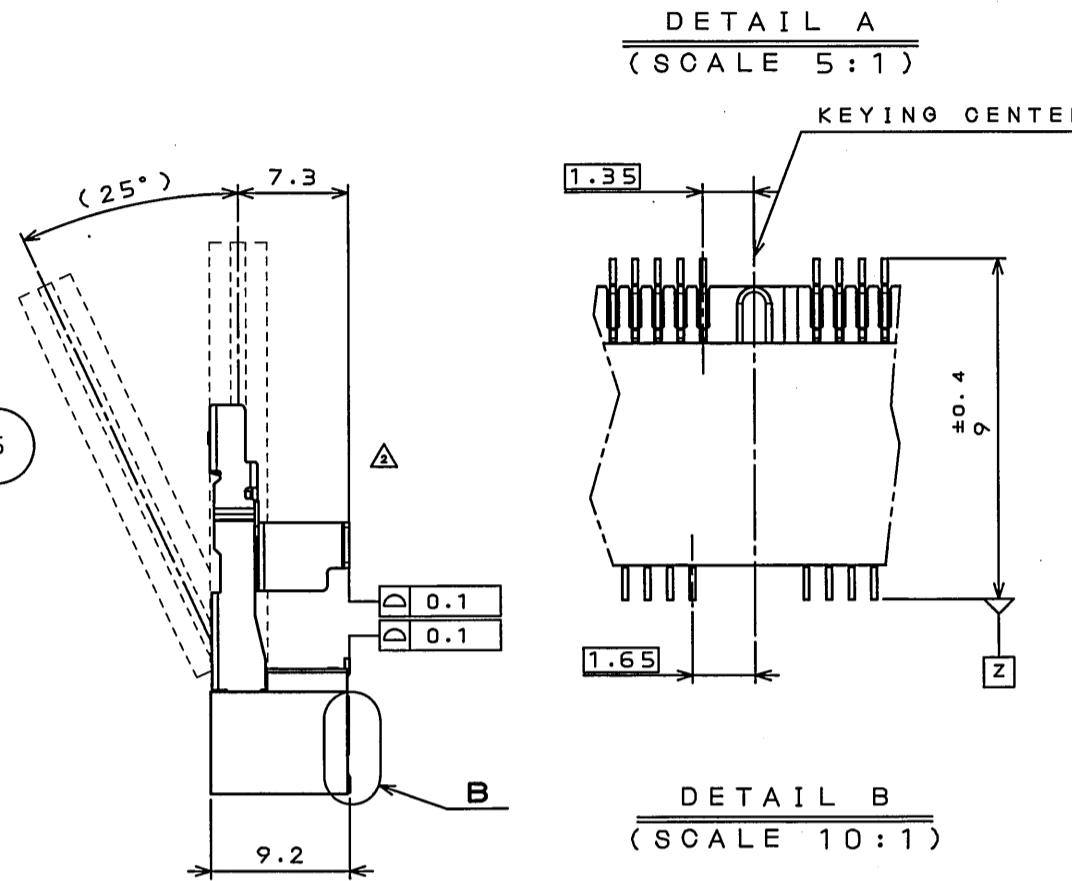
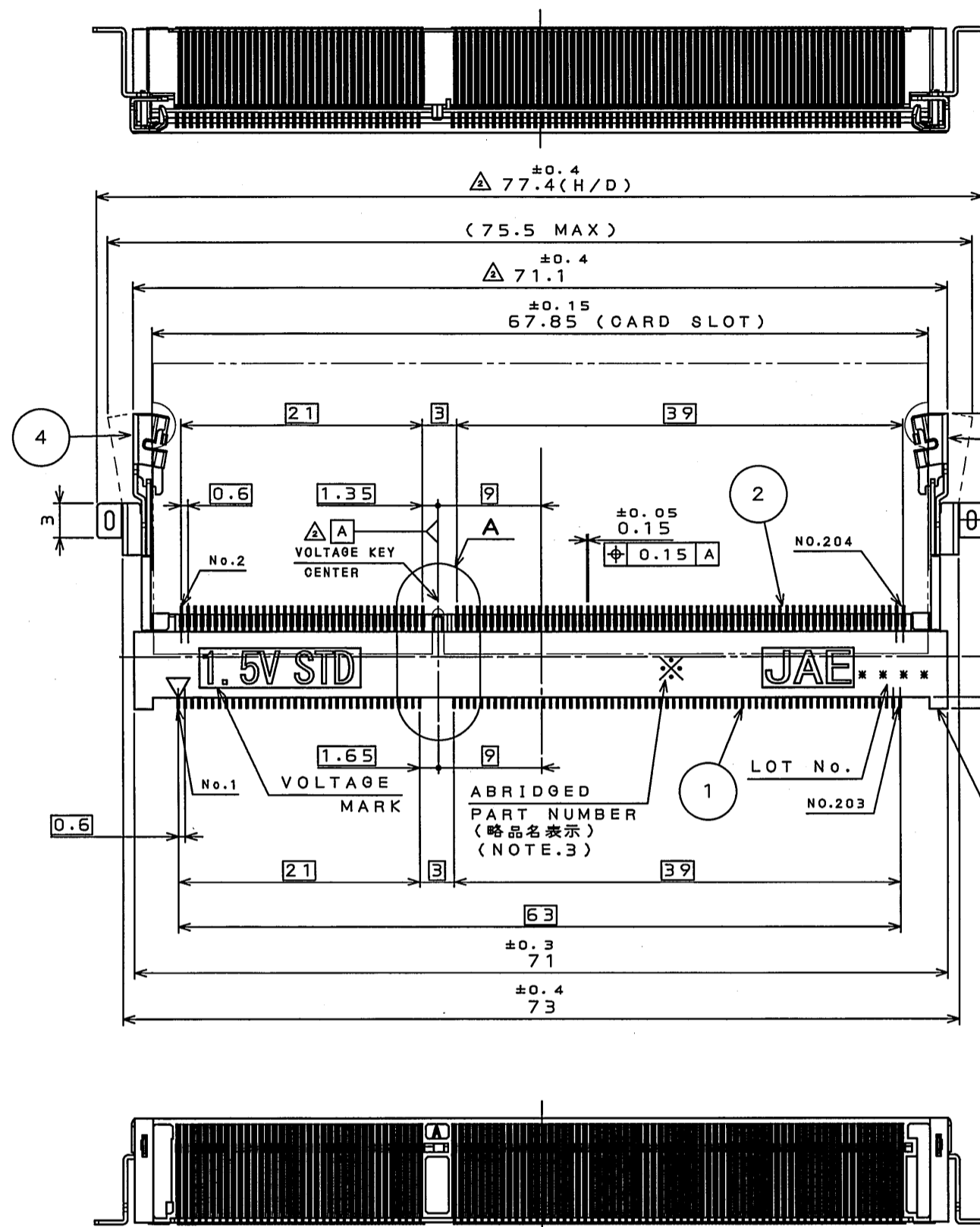
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



REV.	DATE	DCN NO.	DESCRIPTION	DR.	CHK.	APPD.	APPR.
2	10.Feb.2011	071605	LATCH SHAPE CHANGE AND GEOMETRY ALLOWANCE ADD		R.KATOU		T.Shindou

APPLICABLE DIMM(REF.)



APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)

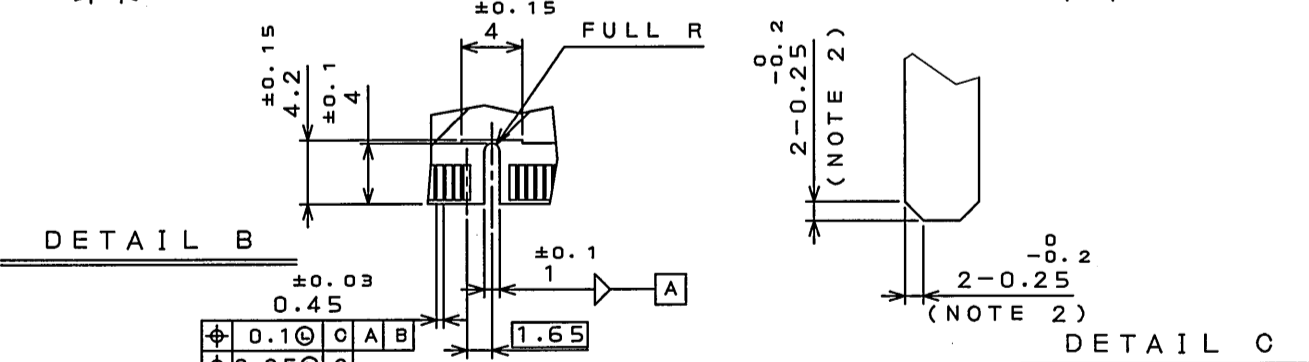
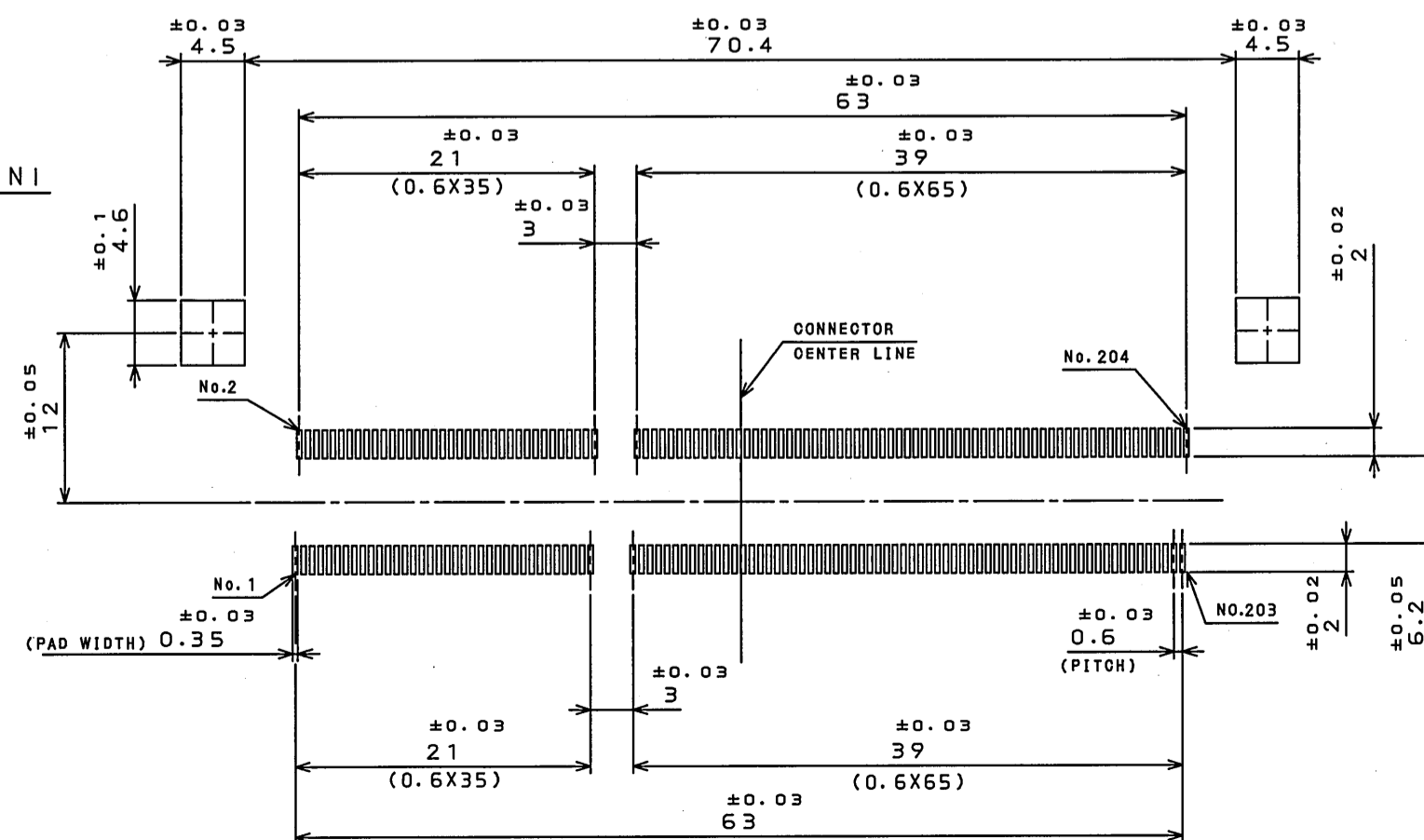
DESIGNATION

MM80-204B1-E1	CONTACT FINISH 接点仕上げ 1:Au(0.1μm MIN) OVER Ni
SERIES シリーズ	MODIFY CODE モディファイコード E:9.2mm HIGHT
NO. OF CONTACTS 芯数	KEYING TYPE キイタイプ 1:1.5V
SOCKET TYPE ソケットタイプ B:LATCH TYPE SMT	

NOTE 1. CARD THICKNESS INCLUDES PAD PLATING.
NOTE 2. BEVEL MUST BE FREE OF CUTTING BURRS.
NOTE 3. ABRIDGED PART NUMBER IS DISPLAYED AS BELOW

MM80-204B1-E1
ABRIDGED PART NUMBER

注1. カートの厚みは、接点部パッドのめっきを含んだ厚みを適用します。
注2. 先端面取り部は、バリなど無き事。
注3. 略品名表示は下記下線部分を表示します。
MM80-204B1-E1
略品名



NO.	DESCRIPTION	QTY.	MATERIAL	FINISH	REMARKS
5	LATCH 2	1	STAINLESS	TIN PLATING	
4	LATCH 1	1	STAINLESS	TIN PLATING	
3	INSULATOR	1	GLASS FILLED LOP		
2	LOWER CONTACT	102	COPPER ALLOY	CONTACT AREA: Au(0.1μm MIN) OVER NICKEL SOLDERING AREA: GOLD FLASH OVER NICKEL	
1	UPPER CONTACT	102	COPPER ALLOY	CONTACT AREA: Au(0.1μm MIN) OVER NICKEL SOLDERING AREA: GOLD FLASH OVER NICKEL	

仕様書(SPECIFICATION) JACS-10662	第1版(ORIGINAL DATE) 24.AUG.2010	尺(SCALE) 2:1	シリーズ(SERIES) MM80	備考 日本航空電子工業株式会社
製図 DR.	担当 OHK. R.KATOU	名称(TITLE) MM80-204B1-E1		JAE CONNECTOR DIV. PROPRIETARY. COPYRIGHT (C) 2010, JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
寸法(DIMENSION) 角度(ANGLES)	承認 APPD. T.SHINDOU	図面番号(DRAWING NO.) SJ110292		
公差(GENERAL TOLERANCE)	承認 APPD.	数量(MASS)	版数(REV.) 2	